RD-ECR (Engineering Change Request)

申請人: 韌體課/邱昱智 Tony_Chiu　　表單號: 95　申請日期: 2026-08-27

Proposed Change	☑ Design modification 設計修改 ☐ Second source change 替代料變更 ☐ Material change 材料變更 ☐ Manufacturer change 製造商變更 ☐ Process sequency change 工序變更 ☐ Factory change 工廠變更 ☐ Equipment/Tooling change 設備/模具變更 ☐ Process/Method/Condition change 加工流程/方法 /條件變更 ☐ Others 其他			EC No	EC26081001
-	N/A			Initiator	邱昱智 Tony_Chiu(D0728)
Reason for Change	EDID內容更新			Issue Date	2026-08-27
Model / Part No	1A2A2723Y303200 / PC270529R、1A2A27235303200 / PC270522R			Requester Dept	DV11R008-研發-韌體課
Implementation Type	◉ 1. Immediately Change 立即切換 ○ 2. Running Change 自然切換 ○ 3. Other 其他			-	N/A
PM	潘介翰 Morris_Pan(D0701)	Sales	劉証瑋 Dennis_Liu(D0683)	File attached 附件上傳	Product FW test report_PC... Product FW test report_PC... 客戶郵件內容.pdf 設計變更審查會議記錄_PC2...
Customer Approval	◉ Needed ○ Not needed	Customer Name	Canvys	Customer Sign-off Area 客戶簽核	Engineering SPEC_PC2705... Engineering SPEC_PC2705...
Invalid	◉ No ○ Yes	-	N/A		

Material Change Description 物料變更說明

No	Subassembly	T	PartNo	Description	Qty	Location	Stock	Remark
1	2AAD656R127	B	8EDD656V120	EDID-H (PC270529R)	1.000			
1	2AAD656R127	A	8EDD656V12A	EDID-H (PC270529R)	1.000			
2	2AAD656R127	B	8EDD656V130	EDID-DP (PC270529R)	1.000			
2	2AAD656R127	A	8EDD656V13A	EDID-DP (PC270529R)	1.000			
3	2AAD681R027	B	8EDD681V020	EDID-H (PC270522R)	1.000			
3	2AAD681R027	A	8EDD681V02A	EDID-H (PC270522R)	1.000			
4	2AAD681R027	B	8EDD681V030	EDID-DP (PC270522R)	1.000			
4	2AAD681R027	A	8EDD681V03A	EDID-DP (PC270522R)	1.000			

Engineering Change Assessment Item List 工程變更評估項目清單

1. Application for Revision of Specification or Drawing(s) for delivery 是否有修改交貨的規格或圖面	1.Confirm	○ Yes ◉ No need	1.Remark	No need
2. Standards or Regulatories impact 是否有評估適用之標準或主管機關之相關法規的申請	2.Confirm	○ Yes ◉ No need	2.Remark	無影響
3. Change point of PCB mounting PCBA插件位置是否變更	3.Confirm	○ Yes ◉ No need	3.Remark	No need
4. PCBA Process Changes PCBA製程是否變更	4.Confirm	○ Yes (Continue checking below) ◉ No	4.Remark	無影響
_ 4-1) Change of Reflow temperature 迴焊溫度是否變更	4-1 Confirm	○ Yes ◉ No need	4-1.Remark	無影響
_ 4-2) Change of bonding temperature 膠合溫度是否變更	4-2 Confirm	○ Yes ◉ No need	4-2.Remark	無影響
_ 4-3) Change of Manual Soldering temperature 人工手焊工具之溫度是否變更	4-3 Confirm	○ Yes ◉ No need	4-3.Remark	無影響

_ 4-4) Change of storage condition after protection humidity package 防潮包裝完成後的儲存條件是否變更	4-4 Confirm	○ Yes ◉ No need	4-4.Remark	無影響
5. Reliability test report(Test result and data) 是否有可靠性測試報告(測試結果及數據)	5.Confirm	◉ Yes ○ No need	5.Remark	參考附件
6. Process FMEA(Medical only) 是否有進行製程失效模式與效應分析	6.Confirm	○ Yes ◉ No need	6.Remark	No need
7. Design FMEA(Medical only) 是否有進行設計失效模式與交應分析	7.Confirm	○ Yes ◉ No need	7.Remark	No need
8. Risk Management(Medical only) 是否有進行風險管理評估	8.Confirm	○ Yes ◉ No need	8.Remark	No need
9. Change points due to the modification 是否此修改會延伸導致其他變更點	9.Confirm	○ Yes ◉ No need	9.Remark	No need
10. Initial Supply Control implements plan or result 是否有實施供料控制評估	10.Confirm	◉ Yes ○ No need	10.Remark	導入工單1007705，1007708
_ 10-1) Confirm the work order or order number or date for the implementation start of the engineering change 確認工程變更開始實施之工單或訂單號碼或日期	10-1 Confirm	◉ Yes ○ No need	10-1.Remark	導入工單1007705，1007708
_ 10-2) Coordinate the handling methods for related products and materials 協調相關產品及材料處理方法	10-2 Confirm	○ Yes ◉ No need	10-2.Remark	EDID變更
_ 10-3) Arrange th production schedule 處理生產日程之安排	10-3 Confirm	◉ Yes ○ No need	10-3.Remark	導入工單1007705，1007708
_ 10-4) Control the changed materials 變更材料之管制	10-4 Confrim	○ Yes ◉ No need	10-4.Remark	EDID變更
_ 10-5) Establish relevant execution control records for EC materials, register traceability data for each material 建立有關工程變更物料之相關執行管控記錄、登錄各項物料追溯性資料	10-5 Confirm	◉ Yes ○ No need	10-5.Remark	導入工單1007705，1007708
11. Training Requirement 若此一變更影響製程或檢驗，是否需要再做人員訓練	11.Confrim	○ Yes ◉ No need	11.Remark	No need
12-1. Modification contents(For example, the following documents) 是否有評估此變更之各項相關文件(如下)	12-1 Confirm	☐ QC control plan ☐ Service Manual ☐ Others ☑ Not needed	12-1.Remark	NA
12-2. Modification contents(For example, the following documents) 是否有評估此變更之各項相關文件(如下)	12-2 Confirm	☐ SIP ☑ SOP ☐ Others ☐ No need	12-2.Remark	SOP須變更.
12-3. Modification contents(For example, the following documents) 是否有評估此變更之各項相關文件(如下)	12-3 Confirm	☑ MDF ☑ DMR ☐ Approval Sheet ☐ Engineering Spec ☐ Others ☑ Not needed	12-3.Remark	Not needed
DIVA 鈺緯科技開發股份有限公司		版本：C		表單編號：QR-736-05

簽核列表 ◉ 表格 ○ 圖形

序號	簽核人	簽核結果	簽核意見
1	**王寶源 Rexwang** 二階主管(課/部級)	**同意** 2026-08-27 11:23	
2	**林金封 Jim_Lin** ECR-DQE人員	**同意** 2026-08-27 13:15	N/A
2	**林雪清 Joe_Lin** ECR-DQE人員	**同意** 2026-08-27 13:46	DQE測試報告如附件
2	**呂旻峰 Jack** ECR-DQE人員	**同意** 2026-08-27 15:56	N/A

序號	簽核人	簽核結果	簽核意見
2	**張鈞凱 Ericchang** ECR-DQE人員	**同意** 2026-08-27 16:19	無影響EMI
3	**廖榮棋 Rongchi_Liao** DQE主管	**同意** 2026-08-27 16:35	
4	**劉証瑋 Dennis_Liu** Sales	**同意** 2026-08-27 16:43	
4	**潘介翰 Morris_Pan** PM	**同意** 2026-08-27 17:25	
5	**楊建勛 Michael_Young** R&D Director [通知]	**同意** 2026-08-27 17:25	[通知]
6	**蕭玉桃 Momohsiao** ECR-PIC人員	**同意** 2026-08-28 09:24	
7	**王世炫 Hsuan_Wang** ECR-PE人員	**同意** 2026-08-28 14:59	
8	**林益銓 Nick_Lin** PE	**同意** 2026-08-28 15:21	
9	**黃振哲 Terry_Huang** ECR-PMC人員	**同意** 2026-08-28 16:01	
10	**邱羽萱 Lily_Chiu** PMC	**同意** 2026-08-28 16:37	
11	**郭修榮 Omega_Kuo** PD	**同意** 2026-08-28 17:29	
11	**黃瓊玉 Joannehuang** ECR-PD人員	**同意** 2026-08-28 17:33	
11	**李慧珊 Sandra** ECR-SCM人員	**略過** 2026-08-31 15:40	不涉及採購
12	**李金龍 Kevin_Lee** ECR-QA人員	**同意** 2026-09-01 09:14	
13	**陳泰盛 Tyson_Chen** QA	**同意** 2026-09-01 09:42	
14	**潘介翰 Morris_Pan** 通知PM&PE [通知]	**同意** 2026-09-01 09:42	[通知]
14	**王世炫 Hsuan_Wang** ECR-PE人員 [通知]	**同意** 2026-09-01 09:42	[通知]
15	**劉証瑋 Dennis_Liu** Sales客審	**同意** 2026-09-01 17:30	
16	**楊建勛 Michael_Young** R&D Director	**同意** 2026-09-01 17:35	
17	**蕭玉桃 Momohsiao** ECR-PIC人員	**同意** 2026-09-01 17:41	
18	**邱昱智 Tony_Chiu** SAP核發	**同意** 2026-09-01 17:56	